

Power Inductor

AHP252012BMV-SERIES

1、 Features

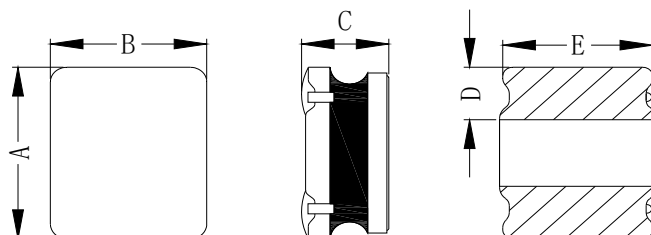
1. This specification applies Low Profile Power Inductors.
2. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
3. High reliability -Reliability tests comply with AEC-Q200



2、 Applications

Automotive applications.

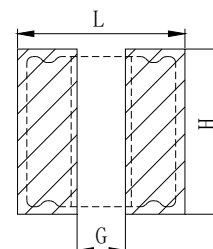
3、 Dimension



Series	*A(mm)	*B(mm)	*C(mm)	D(mm)	E(mm)
AHP252012	2.5±0.2	2.0±0.2	1.0±0.2	0.9±0.3	2.0±0.2

*Dimensions are not including the termination. For maximum overall dimensions with termination , add 0.1mm.

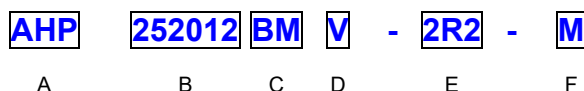
Recommended Land pattern



L(mm)	G(mm)	H(mm)
3.0	0.7	2.5

Note: 1. The above PCB layout reference only.
2. Recommend solder paste thickness at 0.10mm and above.

4、 Part Numbering



- A: Series
- B: Dimension
- C: Type
- D: Code
 - V=Vehicle
- E: Inductance
 - 2R2=2.20uH
- F: Inductance Tolerance
 - K=± 10%, L=± 15%, M=± 20%, Y=± 30%.

5、Specification

TAI-TECH Part Number	Inductance (μ H)	I rms (A)		I sat (A)		DCR ($m\Omega$)	
		typ	Max	typ	Max	typ	Max
AHP252012BMV-R24M	0.24	6.30	5.80	10.00	9.00	18	21.6
AHP252012BMV-R33M	0.33	5.60	5.10	8.70	8.00	24	28.8
AHP252012BMV-R47M	0.47	5.00	4.60	7.30	6.60	30	36
AHP252012BMV-R68M	0.68	4.60	4.20	6.20	5.50	36.5	44
AHP252012BMV-1R0M	1.00	4.00	3.70	5.40	4.80	48	58
AHP252012BMV-1R5M	1.50	3.30	2.90	4.00	3.60	65	78
AHP252012BMV-2R2M	2.20	2.90	2.60	3.10	2.60	92	110
AHP252012BMV-3R3M	3.30	2.50	2.20	2.60	2.20	130	156
AHP252012BMV-4R7M	4.70	1.90	1.70	2.30	2.00	200	240
AHP252012BMV-6R8M	6.80	1.60	1.40	1.80	1.60	300	360
AHP252012BMV-100M	10.0	1.20	1.10	1.40	1.20	450	540

Note:

1. Test frequency : L_s : 1MHz /1.0V.
2. All test data referenced to 25 $^{\circ}$ C ambient.
3. Testing Instrument(or equ) : Agilent 4284A,E4991A,4339B,KEYSIGHT E4980A/AL,chroma3302,3250,16502.
4. Heat Rated Current (I rms) will cause the coil temperature rise approximately ΔT of 40 $^{\circ}$ C
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125 $^{\circ}$ C under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. I rms Testing : Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components.
Therefore temperature rise should be verified in application conditions.
8. Rated DC current: The lower value of I rms and Isat.

11、Typical Performance Curves

